

Bill of Materials

TI DESIGNS TIDA-00779 REV B
High Efficiency and Cost Competitive 3.5kw Power Factor Correction

Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number	Note
1	PCB	Printed Circuit Board	Any	TIDA-00779	Fitted
1	BR1	Diode, Bridge Rectifier, GPP 35A 800V GBJ	Micro Commercial Co	GBJ3508	Fitted
3	C1, C2, C22	CAP, Film, 2.2 μ F, 630 V, +/- 10%, TH	TDK	B32923C3225K	Fitted
1	C3	CAP, Film, 1 μ F, 630 V, +/- 10%, 0.018 ohm, TH	TDK	B32923C3105K	Fitted
3	C4, C5, C18	CAP, ALUMINIUM, RADIAL, 680 μ F, 450 V, 20%, TH	NICHICON	LGG2W681MELC50	Fitted
6	C6, C7, C8, C9, C23, C26	CAP CER 2200PF 400VAC 20% RADIAL DISC 10mm Dia	TDK	CD90ZU2GA222MYNKA	Fitted
1	C10	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0603	MuRata	GRM188R71H472KA01D	Fitted
1	C11	CAP, CERM, 820 pF, 50 V, +/- 10%, X7R, 0603	Kemet	C0603C821K5RACTU	Fitted
2	C12, C17	CAP, CERM, 1 μ F, 25 V, +/- 10%, X7R, 0603_095	Kemet	C0603C105K3RACTU	Fitted
1	C13	CAP, CERM, 0.39 μ F, 16 V, +/- 10%, X7R, 0603	Kemet	C0603C394K4RACTU	Fitted
1	C14	CAP, CERM, 8.2 μ F, 25 V, +/- 10%, X5R, 0603	AVX	0603ZD475KAT2A	Fitted
1	C15	CAP, CERM, 2700 pF, 100 V, +/- 5%, X7R, 0603	AVX	06031C272JAT2A	Fitted
1	C16	CAP, CERM, 0.1 μ F, 16 V, +/- 5%, X7R, 0603	AVX	0603YC104JAT2A	Fitted
1	C19	CAP, AL, 10 μ F, 35V, +/-20%, 0.95 ohm, TH	Nichicon	UPW1V100MDD6	Fitted
1	C20	CAP, CERM, 10 μ F, 25 V, +/- 10%, X5R, 0805	TDK	C2012X5R1E106K125AB	Fitted
1	C21	CAP, CERM, 1000 pF, 1000 V, +/- 5%, X7R, 1206	AVX	1206AC102KAT1A	Fitted
1	C24	CAP, CERM, 0.47 μ F, 16 V, +/- 10%, X7R, 0603	Kemet	C0603C474K4RACTU	Fitted
1	C25	CAP CER 10UF 50V 20% X5R 1206	Taiyo Yuden	UMK316BBJ106ML-T	Fitted
1	C27	CAP, CERM, 220 pF, 50 V, +/- 10%, X7R, 0603	TDK	C1608X7R1H221K	Fitted
1	C28	CAP, CERM, 1 μ F, 50 V, +/- 10%, X7R, 0603	Taiyo Yuden	UMK107AB7105KA-T	Fitted
2	D1, D3	Diode, 600 V, 30 A, TH	Fairchild	FFH30S60S	Fitted
1	D2	Diode, Switching-Bridge, 600 V, 3 A, TH	Vishay-Semiconductor	1N5406	Fitted
3	D4, D8, D10	Diode, Schottky, 30V, 0.2A, SOD-323	Fairchild	BAT54HT1G	Fitted
1	D5	Diode, Ultrafast, 100V, 0.15A, SOD-123	Diodes Inc.	1N4148W-7-F	Fitted
2	D6, D7	Diode, P-N, 1000 V, 1 A, 3.9x1.7x1.8mm	Comchip Technology	CGRM4007-G	Fitted
1	D9	Diode, Zener, 12V, 300mW, SOD-323	NXP Semiconductor	BZX384-C12,115	Fitted
2	D11, D12	Diode, Switching, 100 V, 0.2 A, SOD-323	Micro Commercial Components	MMDL914-TP	Fitted
1	F1	FUSE CLIP, CARTRIDGE, 250V, 30A, PCB	Littelfuse	30A	Fitted
1	HS1	HEATSINK ALUM Black Anodized, Board Mount	Assmann	Customized	Fitted
1	J3	Header, 100mil, 6x1, Tin, TH	Sullins Connector Solutions	PEC06SAAN	Fitted
3	R4, R5, R45	RES, 0.01, 1%, 5 W, TH	TBD	R01	Fitted
6	R1, R10, R15, R19, R23, R42	RES, 10.0 k, 1%, 0.1 W, 0603	Vishay-Dale	CRCW060310K0FKEA	Fitted
1	L4	Differential inductor, 10 μ H, TH	QingDao YunLu Energy Technology CO.,LTD	Customized	Not-Fitted
1	K1	Single-Pole, 240VAC, 30A	HONGFA	HF105F-1/12DT-1HS	Fitted
1	R2	PTC, 47 ohm	TDK	B470	Fitted
1	L1	INDUCTOR, 790 μ H, 30A, 10%, TH	QingDao YunLu Energy Technology CO.,LTD	029E1-001	Fitted
2	L2, L3	INDUCTOR, CHOKE, COMMON MODE, 2.5 mH, 30 A, TH	QingDao YunLu Energy Technology CO.,LTD	LT38-4P-014	Fitted
2	Q1, Q6	MOSFET, N-CH, 600 V, 37.9 A, TO-247	Infineon Technologies	IPW60R099P6	Fitted
1	Q2	Transistor, PNP, 40V, 0.2A, SOT-23	Fairchild Semiconductor	MMBT3906	Fitted
2	Q3, Q5	MOSFET, N-CH, 60V, 0.17A, SOT-23	Diodes Inc.	2N7002-7-F	Fitted
1	Q4	Transistor, NPN, 45 V, 0.1 A, SOT-23	ON Semiconductor	BC847CLT1G	Not Fitted

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